

GMM – Fachgruppe 1.2.3 Abscheide- und Ätzverfahren

25. Workshop

Wednesday, December 6, 2023

Fraunhofer IISB, Schottkystraße 10, 91058 Erlangen, Germany

9:00 **Welcome**

Werner Robl, *Infineon Technologies AG, Regensburg, Germany*
Susanne Oertel, *Fraunhofer IISB, Erlangen, Germany*

9:05 **Rückblick auf 25 GMM-Workshops "Abscheide- und Ätzverfahren"**

Werner Robl, *Infineon Technologies, Regensburg* & Georg Roeder, *Fraunhofer IISB, Erlangen*

Wide-Bandgap Semiconductor Technology

9:30 **Steady-State Etch for GaN/AlGaN Applications**

Richard Barnett, *KLA/SPTS Technologies, Newport, United Kingdom*

10:00 **Etch & Deposition Process Solutions for SiC Power Applications**

Richard Barnett, *KLA/SPTS Technologies, Newport, United Kingdom*

10:30 Coffee Break

11:00 **The Advantages of High-k Dielectrics for SiC Power MOSFETs**

Moritz Wehrle, *Hitachi Energy, Aargau, Switzerland*

11:30 **Ion Traps for Quantum Computing**

Helmut Schönherr, *Infineon Technologies Austria, Villach, Austria*

12:00 Lunch Break

New Unit Processes for Deposition and Etch

13:00 **Pulsed Laser Deposition**

Raimund Förg, *Technische Hochschule Deggendorf / Technologiecampus Teisnach Sensorik, Deggendorf*

13:30 **Pulsed Laser Deposition - what's next?**

Renzo Stheins, *Lam Research, Enschede Overijssel, Netherlands*

14:00 Coffee Break

14:30 **Plasma-Etch End-Pointing in III-V Compound Semiconductor-Based Device Structures**

Marcello Binetti, *LayTec, Berlin*

15:00 **Shifting Supply Chains for 200 mm or Smaller Legacy PVD, PECVD and Plasma Etch Equipment**

Toni Sandbrink-Koblenz, *memsstar Ltd., Livingston, United Kingdom*

15:30 **FALP - Fast Atomic Layer Processing: PEALD (Plasma Enhanced Atomic Layer Deposition) & ALE (Atomic Layer Etch) in one Chamber!**

Stephan Wege, *plasway-Technologies, Bannewitz*

16:00 **Final Discussion, Closing Remarks**

16:15 **End of Workshop**